



Semiconductor Materials Information

CMP CONSUMABLES Pads & Slurry Only 2015

**Techcet Group
Critical Materials Report**

Prepared by

SUE DAVIS

WITH CONTRIBUTIONS FROM

MICHAEL FURY, Ph.D., BOB ROBERTS, & KAREY HOLLAND, Ph.D.

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+1-480-336-2160

info@techcet.com

www.techcet.com

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